Apprenticeship

ELECTRONICS ASSEMBLER OCCUPATIONAL ANALYSIS FOR SASKATCHEWAN

March 16, 2011

SASKATCHEWAN APPRENTICESHIP AND TRADE CERTIFICATION COMMISSION

- **BLOCK** is the largest division within the analysis and reflects a distinct operation relevant to the occupation.
- A. **TASK** is the distinct activity that, combined with others, makes up the logical and necessary steps the worker is required to perform to complete a specific assignment within a "BLOCK".
- B. **SUB-TASK** is the smallest division into which it is practical to subdivide any work activity and, combined with others, fully describes all duties constituting a "TASK".
- C. **SUPPORTING KNOWLEDGE AND ABILITIES** is the element that an individual must acquire to adequately perform the task is identified under this heading.
- D. SAFETY safe working procedures and conditions, accident prevention and the preservation of health are of primary importance to industry in Saskatchewan and Canada. These responsibilities are shared and require the joint efforts of government, employers and employees. It is imperative that all parties become aware of circumstances that may lead to injury or harm. Safe learning experiences and environments can be created by controlling the variables and behaviours that may contribute to an accident or injury.

It is generally recognized that a safety-conscious attitude and work practices contribute to a healthy, safe and accident-free working environment.

It is imperative to apply and be familiar with the Occupational Health and Safety Act and Regulations. As well, it is essential to determine workplace hazards and take measures to protect oneself, co-workers, the public and the environment.

As safety education in an integral part of training in all jurisdictions, personal safety practices are not recorded in this document. However, the technical safety aspect relating to each task and sub-task are included throughout this analysis. (As adapted from Human Resources Development Canada; Occupational Analyses Series (Red Seal Interprovincial Standards.)

BLOCK A

PREPARES FOR PRODUCTION

| Task 1 | Follow | vs company po | licies and production flow requirements |
|----------|--------|---|--|
| Sub-task | 1.01 | Follows safety | procedures |
| | | Supporting Kr | nowledge and Abilities |
| | | 1.01.01 1.01.02 1.01.03 1.01.04 | Knowledge of WHMIS Knowledge of CSA Knowledge of hazards in lifting/carrying material Knowledge of safe practices |
| Sub-task | 1.02 | Follows delive | ery schedules |
| | | Supporting Kr | nowledge and Abilities |
| | | 1.02.01 1.02.02 1.02.03 | Knowledge of order tracking systems Ability to estimate time requirements Knowledge of customer requirements |
| Sub-task | 1.03 | Follows Quali | ty Assurance procedures |
| | | Supporting Kr | nowledge and Abilities |
| | | 1.03.01 1.03.02 1.03.03 1.03.04 1.03.05 | Knowledge of quality management systems Knowledge of ISO Knowledge of the purpose of traceability Ability to use sampling plans such as ANSI, mil spec. Ability to recommend manufacturability adjustments |
| Sub-task | 1.04 | Understands e | mployer organization |
| | | Supporting Kr | nowledge and Abilities |
| | | 1.04.01 1.04.02 1.04.03 | Knowledge of company organization charts Knowledge of Human Resources policies Knowledge of employer practices and procedures |

| Sub-task | 1.05 | Follows mate | erial management and handling policies |
|----------|--------|--|---|
| | | Supporting K | nowledge and Abilities |
| | | 1.05.01 1.05.02 1.05.03 1.05.04 | Knowledge of just-in-time Knowledge of part numbering systems Knowledge of bill of material process Knowledge of batch and one piece flow processing |
| | | 1.05.05 | systems Knowledge of processes such as Kan Ban, Floor stock etc. |
| | | 1.05.06 1.05.07 1.05.08 | Ability to package assemblies Ability to use material handling equipment Knowledge of packaging materials and their applications such as bubble pack, static shielding/dissipative |
| | | 1.05.09 | Knowledge of correct packaging techniques |
| Sub-task | 1.06 | Understands | contract requirements |
| | | Supporting K | nowledge and Abilities |
| | | 1.06.01 | Knowledge of unique specifications such as military, aerospace etc. |
| | | 1.06.02 | Knowledge of lead free export requirements |
| Task 2 | Identi | fies materials and components | |
| Sub-task | 2.01 | Ability to identify fasteners | |
| | | Supporting K | nowledge and Abilities |
| | | 2.01.01 2.01.02 | Knowledge of fastener types Knowledge of fastener uses |
| Sub-task | 2.02 | Ability to ide | ntify electronic devices and materials |
| | | Supporting K | nowledge and Abilities |
| | | 2.02.01 2.02.02 2.02.03 2.02.04 2.02.05 2.02.06 | Knowledge of types of electronic devices Knowledge of electronic materials Knowledge of solder types Ability to interpret colour coding Ability to interpret component ID markings Ability to interpret component orientation/polarity indicators |

| | | 2.02.07 | Knowledge of solder/flux compatibility |
|----------|--------|-------------------------|--|
| Sub-task | 2.03 | Ability to ide | ntify hand tools |
| | | Supporting K | nowledge and Abilities |
| | | 2.03.01 2.03.02 | Knowledge of hand tools types Knowledge of soldering irons and tips |
| Sub-task | 2.04 | Ability to ide | ntify power tools |
| | | Supporting K | nowledge and Abilities |
| | | 2.04.01 2.04.02 | Knowledge of power tool types Knowledge of power tool uses |
| Task 3 | Interp | orets documen | tation |
| Sub-task | 3.01 | Reads schema | ntics |
| | | Supporting K 3.01.01 | nowledge and Abilities Knowledge of schematic symbols and reference designators |
| | | 3.01.02 | Ability to interpret from a schematic |
| | | 3.01.03 | Knowledge of electronics |
| | | 3.01.04 | Knowledge of basic and configuration math |
| Sub-task | 3.02 | Reads wiring | lists |
| | | Supporting K | nowledge and Abilities |
| | | 3.02.01 | Ability to determine wire length |
| | | 3.02.02 | Ability to determine wire gauge |
| | | 3.02.03 | Ability to determine termination instructions |
| | | 3.02.04 | Ability to interpret wiring from the wire list |
| Sub-task | 3.03 | Reads engine | ering assembly drawings |
| | | Supporting K | nowledge and Abilities |
| | | 3.03.01 3.03.02 | Ability to interpret mechanical drawings Ability to read circuit card layouts |

| Sub-task | 3.04 | Reads work in | nstructions |
|----------|--------|--|--|
| | | Supporting Ki | nowledge and Abilities |
| | | 3.04.01 3.04.02 3.04.03 | Ability to decipher sequence of tasks Ability to read with comprehension Knowledge of best practises |
| Sub-task | 3.05 | Interprets wor | kmanship standards |
| | | Supporting Ki | nowledge and Abilities |
| | | 3.05.01 3.05.02 3.05.03 3.05.04 3.05.05 3.05.06 | Knowledge of international standards Knowledge of corporate and/or client standards Ability to use measurement tools Ability to use magnification tools Ability to determine pass/fail Ability to determine which workmanship standard applies (Lead/Lead free, Client/Internal) |
| Sub-task | 3.06 | Operates com | puters |
| | | Supporting K | nowledge and Abilities |
| | | 3.06.01 3.06.02 3.06.03 3.06.04 | Ability to use the internet Ability to use e-mail Ability to use office suite Ability to use automated test software programs |
| Task 4 | Follov | vs ESD (electro | ostatic discharge) procedures |
| Sub-task | 4.01 | Verifies ESD | equipment functionality |
| | | Supporting Ki | nowledge and Abilities |
| | | 4.01.01 4.01.02 | Knowledge of ESD equipment Ability to perform ESD equipment test |
| Sub-task | 4.02 | Uses ESD ma | terials and equipment |
| | | Supporting Ki | nowledge and Abilities |
| | | 4.02.01 4.02.02 4.02.03 4.02.04 | Knowledge of ESD materials Knowledge of ESD policies Knowledge of ESD and its potential damage Ability to select appropriate precautions |

Sub-task 4.03 Follows specialized handling procedures

Supporting Knowledge and Abilities

| 4.03.01 | Knowledge of clean room procedures |
|---------|---|
| 4.03.02 | Knowledge of moisture sensitive components |
| 4.03.03 | Ability to use specialized handling processes |

BLOCK B

PRODUCES CIRCUIT CARDS

| Task 5 | Builds | s cards as requ | ired | |
|---------------|--------|-------------------------------|--|--|
| Sub-task | 5.01 | Prepares comp | ponents | |
| | | Supporting Kı | nowledge and Abilities | |
| | | 5.01.01 5.01.02 5.01.03 | Ability to tin leads (using solder pot/iron) Ability to pre-form leads using manual tools Knowledge of component handling requirements/precautions | |
| | | 5.01.04 5.01.05 | Ability to select components Ability to determine component preparation requirements | |
| | | 5.01.06 | Knowledge of pre-forming leads using machine pre- forming equipment | |
| Sub-task 5.02 | | Populates cards | | |
| | | Supporting Kı | nowledge and Abilities | |
| | | 5.02.01 5.02.02 | Ability to insert components by hand Knowledge of the operation of semi-automated and automated insertion equipment | |
| | | 5.02.03 | Knowledge of the operation and adjustments required by pick and place machines | |
| Sub-task | 5.03 | Performs seco | and assembly | |
| | | Supporting Kı | nowledge and Abilities | |
| | | 5.03.01 5.03.02 | Ability to install and secure hardware Ability to install cable/wires including hand soldering and securing | |
| | | 5.03.03 5.03.04 5.03.05 | Ability to insert socketed components Ability to apply labels Ability to apply compounds such as heat sink compound | |

| Task 6 | Hand | solders circuit | t cards using tin/lead technology |
|----------|------|-------------------------|--|
| Sub-task | 6.01 | Produces CCA technology | A's (circuit card assemblies) with surface mount |
| | | Supporting K | nowledge and Abilities |
| | | 6.01.01 | Ability to select and operate hand soldering equipment |
| | | 6.01.02 | Ability to inspect for defects |
| Sub-task | 6.02 | Reworks CCA | A's with surface mount technology |
| | | Supporting K | nowledge and Abilities |
| | | 6.02.01 | Ability to remove surface mount components (excluding BGA's) |
| | | 6.02.02 | Ability to remove solder |
| | | 6.02.03 | Ability to perform solder joint touch-up |
| Sub-task | 6.03 | Repairs CCA | 's with surface mount technology |
| | | Supporting K | nowledge and Abilities |
| | | 6.03.01 | Ability to identify major faults and damage |
| | | 6.03.02 | Ability to replace components |
| | | 6.03.03 | Ability to repair tracks and lands |
| | | 6.03.04 | Knowledge of repair procedures |
| Sub-task | 6.04 | Produces CCA | A's with through-hole technology |
| | | Supporting K | nowledge and Abilities |
| | | 6.04.01 | Ability to identify component and solder side of CCA |
| | | 6.04.02 | Ability to select and operate hand soldering equipment |
| | | 6.04.03 | Ability to inspect for defects |
| Sub-task | 6.05 | Reworks CCA | A's with through-hole technology |
| | | Supporting K | nowledge and Abilities |
| | | 6.05.01 | Ability to remove through-hole components |
| | | 6.05.02 | Ability to perform solder joint touch-up |
| | | 6.05.03 | Ability to remove solder |

| Sub-task | 6.06 | Repairs CCA's with through-hole technology | |
|----------|------|---|--|
| | | Supporting Knowledge and Abilities | |
| | | 6.06.01 6.06.02 6.06.03 6.06.04 | Ability to identify major faults and damage Ability to replace components Ability to repair tracks and barrels Knowledge of repair procedures |
| Task 7 | Hand | solders circuit | cards using lead free technology |
| Sub-task | 7.01 | Produces CCA's (circuit card assemblies) with surface moun technology | |
| | | Supporting Kr | nowledge and Abilities |
| | | 7.01.01 | Ability to select and operate hand soldering |
| | | 7.01.02 | equipment Ability to inspect for defects |
| Sub-task | 7.02 | Reworks CCA | 's with surface mount technology |
| | | Supporting Kı | nowledge and Abilities |
| | | 7.02.01 | Ability to remove surface mount components |
| | | 7.02.02 | (excluding BGA's) Ability to remove solder |
| | | 7.02.03 | Ability to perform solder joint touch-up |
| Sub-task | 7.03 | Repairs CCA' | s with surface mount technology |
| | | Supporting Kr | nowledge and Abilities |
| | | 7.03.01 7.03.02 7.03.03 7.03.04 | Ability to identify major faults and damage Ability to replace components Ability to repair tracks and lands Knowledge of repair procedures |

| Sub-task | 7.04 | Produces CC | A's with through-hole technology |
|----------|------|--------------------|--|
| | | Supporting K | nowledge and Abilities |
| | | 7.04.01 | Ability to identify component and solder side of CCA |
| | | 7.04.02 | Ability to select and operate hand soldering |
| | | 7.04.03 | equipment Ability to inspect for defects |
| Sub-task | 7.05 | Reworks CCA | A's with through-hole technology |
| | | Supporting K | nowledge and Abilities |
| | | 7.05.01 | Ability to remove through-hole components |
| | | 7.05.02 7.05.03 | Ability to perform solder joint touch-up Ability to remove solder |
| | | 7.03.03 | Nomity to remove solder |
| Sub-task | 7.06 | Repairs CCA | 's with through-hole technology |
| | | Supporting K | nowledge and Abilities |
| | | 7.06.01 | Ability to identify major faults and damage |
| | | 7.06.02 | Ability to replace components |
| | | 7.06.03 7.06.04 | Ability to repair tracks and barrels Knowledge of repair procedures |
| | | 7.00.04 | Knowledge of Tepair procedures |
| Task 8 | Mach | ine solders cir | cuit cards |
| Sub-task | 8.01 | Prepares print | ted wiring board (PWB) |
| | | Supporting K | nowledge and Abilities |
| | | 8.01.01 | Ability to select appropriate solder paste (tin/lead, lead free) |
| | | 8.01.02 | Ability to apply solder paste (hand/machine) |
| | | 8.01.03 | Knowledge of stencil handling procedures |
| | | 8.01.04 8.01.05 | Ability to inspect solder paste application Ability to heat treat PWB's |
| | | 8.01.06 | Ability to mask PWB's |
| | | | - |

Sub-task 8.02 Wave solders using various wave soldering equipment Supporting Knowledge and Abilities 8.02.01 Ability to perform pre-wave inspection 8.02.02 Knowledge of fluxes, solders, oils, temperatures, and jigs 8.02.03 Knowledge to prepare/set-up the wave soldering equipment (machine/mini wave/selective wave soldering) 8.02.04 Knowledge of techniques used to run wave soldering equipment Ability to perform visual inspection 8.02.05 Knowledge of equipment maintenance (does not 8.02.06 include major repairs/maintenance/overhauls) Sub-task 8.03 Reflow solders circuit cards Supporting Knowledge and Abilities 8.03.01 Ability to perform pre-reflow inspection Knowledge of temperature profiles for reflow ovens 8.03.02 Knowledge of oven operation and adjustment 8.03.03 8.03.04 Ability to perform visual inspection Knowledge of manufacturability requirements 8.03.05 Knowledge of the use of x-ray machines and/or Ball 8.03.06 Grid Array (BGA) inspection tools to inspect BGA's Sub-task 8.04 Selective solders circuit cards (non-wave) Supporting Knowledge and Abilities 8.04.01 Knowledge of non-wave selective solder technology and operation Knowledge of fluxes, solders, temperatures, and 8.04.02 jigs

Knowledge of machine set up Ability to perform visual inspection

8.04.03

8.04.04

| Task 9 | Cleans | s cards after p | roduction |
|----------|--------|--|--|
| Sub-task | 9.01 | Hand cleans CCA's | |
| | | Supporting Ki | nowledge and Abilities |
| | | 9.01.01 9.01.02 | Ability to identify contaminant type Ability to select and apply cleaning method/agent |
| Sub-task | 9.02 | Machine clear | ns cards |
| | | Supporting Ki | nowledge and Abilities |
| | | 9.02.01 9.02.02 | Knowledge of automated cleaning technology Knowledge of machine operation including board placement requirements |
| Task 10 | | Applies envir | conmental coatings to cards |
| Sub-task | 10.01 | Sprays cards | |
| | | Supporting Kı | nowledge and Abilities |
| | | 10.01.01 | Knowledge of conformal coating spray equipment for CCA's (cans/bulk application equipment) |
| | | 10.01.02 10.01.03 | Ability to identify defects Knowledge of touch-up coating techniques |
| Sub-task | 10.02 | Dips cards | |
| | | Supporting Ki | nowledge and Abilities |
| | | 10.02.01 10.02.02 10.02.03 10.02.04 | Knowledge of coating thickness requirements Knowledge of dipping equipment operation Ability to identify defects Knowledge of touch up coating techniques |
| Sub-task | 10.03 | Reworks envi | ronmental coatings |
| | | Supporting Ki | nowledge and Abilities |
| | | 10.03.01 10.03.02 | Knowledge of coating removal techniques Knowledge of conformal coating touch up |

Sub-task 10.04 Dispense potting compound

Supporting Knowledge and Abilities

| 10.04.01 | Knowledge of potting compound technology |
|----------|---|
| 10.04.02 | Knowledge of unit preparation for potting |
| | compound |
| 10.04.03 | Knowledge of potting compound machine operation |

BLOCK C PRODUCES CABLES, WIRES AND HARNESSES

| Task 11 | | Prepares cab | les |
|----------|-------|--|---|
| Sub-task | 11.01 | Cuts cables | |
| | | Supporting K | nowledge and Abilities |
| | | 11.01.01 11.01.02 11.01.03 11.01.04 11.01.05 | Ability to identify cable/wire types Ability to determine cable/wire lengths Knowledge of metric/imperial systems Ability to select and operate manual cutters (both single and multiple conductors) Knowledge of machine cutters (both single and multiple conductors) |
| Sub-task | 11.02 | Strips cables | |
| | | Supporting K | nowledge and Abilities |
| | | 11.02.01 11.02.02 | Ability to determine strip length Ability to select and operate manual stripping equipment for both single and multiple conductor cables/wires |
| | | 11.02.03 | Ability to inspect strip and adjust equipment if required |
| | | 11.02.04 | Knowledge of machine stripping equipment for both single and multiple conductor cables/wires |
| Sub-task | 11.03 | Tins cables | |
| | | Supporting K | nowledge and Abilities |
| | | 11.03.01 11.03.02 | Ability to inspect a tined wire Ability to tin cables/wires |

| Sub-task | 11.04 | Labels cables | |
|----------|-------|--|--|
| | | Supporting Knowledge and Abilities | |
| | | 11.04.01 | Ability to retrieve cable/wire identification |
| | | 11.04.02 11.04.03 | information from paper and electronic sources Ability to apply information to labels Ability to apply labels |
| Task 12 | | Terminates o | eables |
| Sub-task | 12.01 | Solders connectors | |
| | | Supporting K | nowledge and Abilities |
| | | 12.01.01 12.01.02 12.01.03 | Ability to identify and select connectors Ability to select and perform soldering technique Ability to inspect solder connection |
| Sub-task | 12.02 | Crimps connectors | |
| | | Supporting K | nowledge and Abilities |
| | | 12.02.01 12.02.02 12.02.03 | Ability to identify and select connectors Ability to select and operate crimping tool Ability to inspect/test crimp |
| Sub-task | 12.03 | Attaches heat shrink (reflow) connectors | |
| | | Supporting K | nowledge and Abilities |
| | | 12.03.01 12.03.02 12.03.03 | Ability to identify and select connector Ability to install reflow connectors Ability to inspect/test connection |
| Sub-task | 12.04 | Attaches mec | hanical terminations |
| | | Supporting Knowledge and Abilities | |
| | | 12.04.01 12.04.02 12.04.03 12.04.04 12.04.05 | Ability to identify and select connector Ability to perform insertions and extractions Ability to select and operate wire tools Ability to assemble backshells Ability to shrink insulation tubing |

Task 13 Assembles harnesses

Sub-task 13.01 Route wires/cables

Supporting Knowledge and Abilities

| 13.01.01 | Ability to select prepared cables |
|----------|---|
| 13.01.02 | Knowledge of bend radius, service loops, breakout |
| | points and cable protection |
| 13.01.03 | Ability to plan assembly for neat appearance and |
| | minimal crossovers |

Sub-task 13.02 Bundle wires/cables

Supporting Knowledge and Abilities

| 13.02.01 | Ability to select and apply lacing techniques |
|----------|---|
| 13.02.02 | Ability to select and apply fasteners such as tie |
| | wraps and velcro |
| 13.02.03 | Ability to inspect installation. |

BLOCK D

ASSEMBLES CHASSIS AND RACKS

| Task 14 | Prepa | res chassis, subassemblies and racks | | |
|----------|---------|--|---|--|
| Sub-task | 14.01 | Assembles chassis and racks | | |
| | | Supporting Kr | nowledge and Abilities | |
| | | 14.01.01 14.01.02 | Ability to select and use hand and power tools Ability to select and install fasteners | |
| Sub-task | 14.02 | Modifies/reworks/repairs metalwork | | |
| | | Supporting Knowledge and Abilities | | |
| | | 14.02.01 | Ability to modify rework or repair such as grinding, cutting, drilling, deburring, filing, bending and punching | |
| | | 14.02.02 | Knowledge of surface touch up techniques (paint/alodyning) | |
| | | 14.02.03 | Knowledge of special fasteners such as clinch nuts, and helicoils | |
| Task 15 | Install | s components | | |
| Sub-task | 15.01 | 1 Installs components by mechanical means | | |
| | | Supporting Knowledge and Abilities | | |
| | | 15.01.01 15.01.02 15.01.03 15.01.04 | Knowledge of hardware stacking Ability to select and install fasteners Knowledge of torque tools Ability to adjust torque settings | |
| Sub-task | 15.02 | Installs compo | onents by adhesives | |
| | | Supporting Knowledge and Abilities | | |
| | | 15.02.01 15.02.02 | Knowledge of glues and adhesives Ability to apply glues and adhesives | |

Sub-task 15.03 Applies labels and markings

| | | Supporting | Knowledge and Abilities |
|----------|-------|---------------|--|
| | | 15.03.01 | Knowledge of marking techniques such as ink stamping, metal stamping, and stencils |
| | | 15.03.02 | Ability to select and apply labels and markings |
| | | 15.03.03 | Knowledge of contractual requirements |
| Sub-task | 15.04 | Installs harr | nesses |
| | | 15.04.01 | Ability to select prepared harnesses |
| | | 15.04.02 | Ability to attach harnesses to subassemblies |
| | | 15.04.03 | Ability to route harnesses |
| | | 15.04.04 | Ability to secure harnesses to chassis/racks |

BLOCK E

TESTS PRODUCTS

| Task 16 | Uses n | Uses multimeter | | |
|----------------------|--------|------------------------------------|--|--|
| Sub-task | 16.01 | Test for contin | nuity | |
| | | Supporting Kr | nowledge and Abilities | |
| | | 16.01.01 16.01.02 16.01.03 | Knowledge of impedance test procedures Ability to use a multimeter to test continuity Ability to use "beep-out boxes" | |
| Sub-task | 16.02 | Test for voltag | ges | |
| | | Supporting Knowledge and Abilities | | |
| | | 16.02.01 16.02.02 | Knowledge of AC/DC theory Ability to use a multimeter to test voltage | |
| Sub-task | 16.03 | Tests for curre | ent | |
| | | Supporting Knowledge and Abilities | | |
| | | 16.03.01 16.03.02 | Knowledge of amperage test procedures Ability to use a multimeter to test current | |
| Sub-task | 16.04 | Tests for diode | e polarity | |
| Supporting Knowledge | | Supporting Kr | nowledge and Abilities | |
| | | 16.04.01 16.04.02 16.04.03 | Knowledge of diode current flow characteristics Knowledge of basic circuits Ability to use a multimeter to test diode polarity | |

| Task 17 | Uses b softwa | pasic electronic test equipment and automated test/programming are | | |
|----------|--|--|---|--|
| Sub-task | 17.01 | Connects DU | T (device under test) to test equipment | |
| | | Supporting K | nowledge and Abilities | |
| | | 17.01.01 17.01.02 | Knowledge of DUT input/output connections Awareness of spectrum and network analyzers, oscilloscopes and power meters | |
| | | 17.01.03 | Awareness of automated test software uses | |
| Sub-task | Sub-task 17.02 Operates test equipment and interpret | | equipment and interprets test results | |
| | | Supporting Knowledge and Abilities | | |
| | | 17.02.01 17.02.02 17.02.03 17.02.04 17.02.05 17.02.06 | Ability to follow test procedures Knowledge of test expectations Ability to determine pass/fail Ability to record test results Ability to document failure mechanism Awareness of tuning circuits | |
| Sub-task | 17.03 | Follows corre | ective procedures when required | |
| | Suppo | | nowledge and Abilities | |
| | | 17.03.01 | Knowledge of non-conforming product handling procedures | |
| | | 17.03.02 | Ability to fill out repair tags or non-conformance reports | |
| Sub-task | 17.04 | Programs dev | rices | |
| | | Supporting Knowledge and Abilities | | |
| | | 17.04.01 | Knowledge of component level micro programming techniques | |
| | | 17.04.02 | Knowledge of CCA level micro programming techniques | |